

ABSTRACT

A film-shaped adhesive which contains a thermosetting resin component and an elastomer and may further contain an inorganic filler is disclosed. The content of the elastomer is 18% by mass or more with respect to the total amount of the film-shaped adhesive. The content of the inorganic filler is 0 to 25% by mass with respect to the total amount of the film-shaped adhesive. A storage modulus at 150°C of a cured product obtained when the film-shaped adhesive is cured under conditions of 140°C and 30 minutes is 80 MPa or more. A thickness of the film-shaped adhesive is 15 μm or less.

Fig. 1